

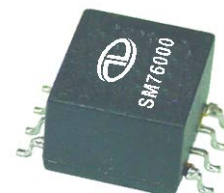
## TELECOM MAGNETICS SM76000

### Features

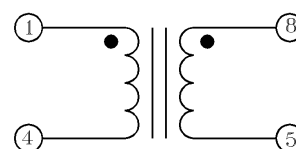
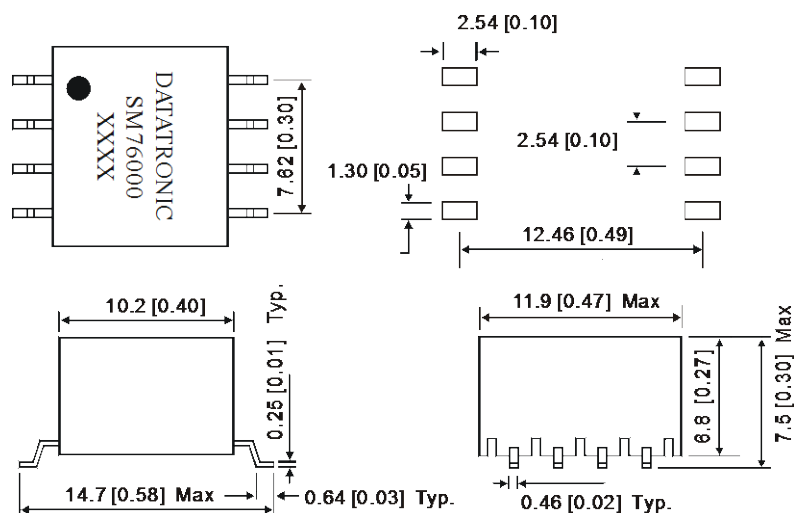
- Designed for Conexant SMART HCF FFI Chipset
- Small size

### ELECTRICAL SPECIFICATIONS AT 25°C

URNS RATIO (1-4) : (8-5)	1 : 2.6 ± 2%
OCL @100kHz, 1V	40μH MIN
LEAKAGE INDUCTANCE @4MHz, 1V	8μH MAX
INTERWINDING CAPACITANCE @1MHz	10pF MAX
SRF	4.0MHz TYP
DCR (1-4)	0.2Ω MAX
DCR (8-5)	0.4Ω MAX
HIPOT PRIMARY & SECONDARY 1 MINUTE	1500VRMS



### OUTLINE DIMENSIONS



**SCHEMATIC**

#### Notes:

- All dimensions are in mm [inches] and typical unless otherwise specified.
- For non-RoHS parts replace SM prefix with 42- (e.g. SM76000 becomes 42-76000)
- Terminal finish is compliant to RoHS requirements. Solder in accordance with J-STD-020C